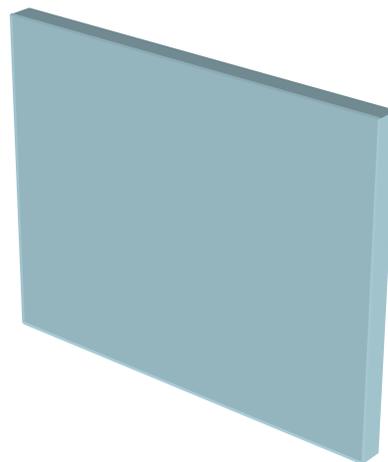


TM-KHC5 Thermally Conductive Gap Filler

TM-KHC5 is an ultra soft silicone interface material with a high thermal conductivity and very high dielectric strength. Through its very high softness and flexibility the material perfectly mates to irregular surface thus filling gaps at very low pressure



Properties

- Very good thermal contact
- Outstanding mechanic stability
- Extraordinary chemical resistance and long-term stability
- Residue-free removal after use

Availability

- Sheet of 300 mm x 400mm for thickness till 0.8 mm
- Sheet of 200 mm x 400mm for thickness over 1 mm
- Die cut parts
- Kiss cut parts on sheet

Application Examples

- Thermal link of :
- MOSFETs or IGBTs
 - Power diodes or AC/DC converters
 - Power modules

- For use in :
- Switch mode power supplies
 - Motor control units
 - Automotive engine management systems
 - UPS units
 - Solar systems

Technical Data



Part	TM-KHC5-XXX
Material	Silicone
Colour	Blue
Specific Gravity [g/cc]	2.7
Tensile strength [Kg/cm²]	55
Thickness [mm]	0.25 mm, 0.8 mm, 1 mm, 2 mm, 3 mm, 4 mm, 5 mm
Hardness [shore 00]	40
UL Flammability [UL 94]	V 0
RoHS Conformity [2002/95/EC]	Yes
Thermal Conductivity [W/mK]	5
Operating Temperature Range [°C]	-40 to +170
Breakdown Voltage [kV/mm]	> 5
Volume Resistivity [Ohm-cm]	3.1x 10¹¹

Create the Part Number

In order to select the right thickness it is necessary to insert 3 numbers as follows:

TM-KHC5-025 for 0.25 mm thickness

TM-KHC5-080 for 0.80 mm thickness

TM-KHC5-100 for 1.00 mm thickness

TM-KHC5-200 for 2.00 mm thickness

TM-KHC5-300 for 3.00 mm thickness

TM-KHC5-400 for 4.00 mm thickness

TM-KHC5-500 for 5.00 mm thickness

Upon request it is possible to have also the intermediate thicknesses (1.5 mm, 2.5 mm, 3.5 mm, 4.5 mm)